IN THE SPECIFICATION:

Please replace paragraph [0011] with the following amended paragraph:

[0011] Yet another embodiment provides a method of regulating temperature of one or more temperature-sensitive components within an enclosure. The method generally includes ~~providing a~~ thermally coupling the temperature-sensitive components to one or more thermoelectric coolers, measuring temperature at or near the temperature-sensitive components, and varying power supplied to thermoelectric coolers thermally coupled with at least one of the temperature-sensitive components, in response to the measured temperature.

Please replace paragraph [0031] with the following amended paragraph:

[0031] For some embodiments, the active temperature regulating components 139 may ~~included~~ include thermoelectric cooling TEC devices, and the control signal may be a modulated DC signal. For some embodiments, cooling and/or heating with the TEC devices may be controlled by varying the duty cycle of a pulse-width-modulated (PWM) DC signal, in order to vary the DC power supplied. TEC devices operate on the Peltier principle: as direct current (DC) passes through a junction of two dissimilar metals, one metal evolves heat, while the other absorbs heat. As shown, the TEC devices may be disposed between the inner enclosure 138 and the finned heat sink 140 (e.g., with a different one of the dissimilar metals thermally coupled to each). Thus, by regulating the DC power supplied, the TEC devices may be configured, in effect, as a heat pump, drawing heat from the inner enclosure 138 to the finned heat sink 140. This effect is reversed when the direction of the DC current is reversed (e.g., the polarity of the DC signal is reversed), which may result in delivery of heat to the optical signal processing components 135.

Please replace paragraph [0037] with the following amended paragraph:

[0037] Referring back to FIG. 3, other heat sinks 141 may be positioned in close proximity to other heat generating components inside the enclosure 130, such as the main controller 134. This allows heat transfer, as shown by arrow 148, to the environment in localized high temperature areas while preventing heat transfer from

outside the enclosure 130 to the inside of the enclosure in areas that have a temperature lower than the outside air temperature. Additionally, insulation 149 may be disposed within the enclosure 130, for example, in an effort to reduce the amount of unwanted heat transfer between the environment and the enclosure.